

IN THE CLAIMS:

Claims 2-8, 10, and 12-17 have been amended herein. All of the pending claims 1 through 17 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Original) A semiconductor device formed by a laser etching process comprising:
providing a substrate having a surface;
forming resist on at least a portion of the surface; and
etching the resist from the surface of the substrate using a laser.
2. (Currently Amended) The method according to claim 1, wherein ~~said the~~ laser comprises a laser associated with an automolding system.
3. (Currently Amended) The method according to claim 1, wherein ~~said the~~ laser includes one of an Nd:YAG laser and an excimer laser.
4. (Currently Amended) The method according to claim 1, wherein ~~said the~~ substrate comprises a ball-grid-array substrate.
5. (Currently Amended) The method according to claim 1, further comprising a vision system for detecting ~~resist the resist~~.
6. (Currently Amended) The method according to claim 5, wherein ~~said the~~ vision system comprises:
providing a laser scanning system; and
detecting changes in a pattern of the substrate.

7. (Currently Amended) A method of enhancing the adhesion of a compound to a surface of a substrate comprising:
providing said the substrate having said the surface; and
roughening the surface of the substrate.

8. (Currently Amended) The method according to claim 7, wherein said roughening comprises removing contamination and foreign particles from said the surface of the substrate.

9. (Original) An automolding system comprising:
providing a substrate having a surface;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

10. (Currently Amended) The automolding system of claim 9, wherein said the laser comprises one of an Nd:YAG laser and an excimer laser.

11. (Original) The automolding system of claim 9, further comprising:
placing the substrate in a mold; and
encapsulating the substrate.

12. (Currently Amended) A semiconductor device formed by a laser etching process on a substrate having a surface comprising:
forming resist on at least a portion of the surface; and
etching the resist from the at least a portion of the surface of the substrate using a laser.

13. (Currently Amended) The method according to claim 12, wherein-said the laser comprises a laser associated with an automolding system.

14. (Currently Amended) The method according to claim 12, wherein-said the laser includes one of an Nd:YAG laser and an excimer laser.

15. (Currently Amended) The method according to claim 12, wherein-said the substrate comprises a ball-grid-array substrate.

16. (Currently Amended) The method according to claim 12, further comprising a vision system for detecting-resist the resist.

17. (Currently Amended) The method according to claim 16, wherein-said the vision system comprises:
providing a laser scanning system; and
detecting changes in a pattern of the substrate.